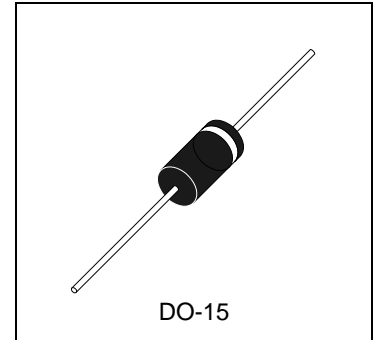




HSB220 thru HSB2100

Schottky Barrier Rectifiers
(Reverse Voltage 20 to 100V, Forward Current 2A)



Features

- Low Forward Voltage Drop
- High Current Capability
- High Reliability
- High Surge Current Capability

Mechanical Data

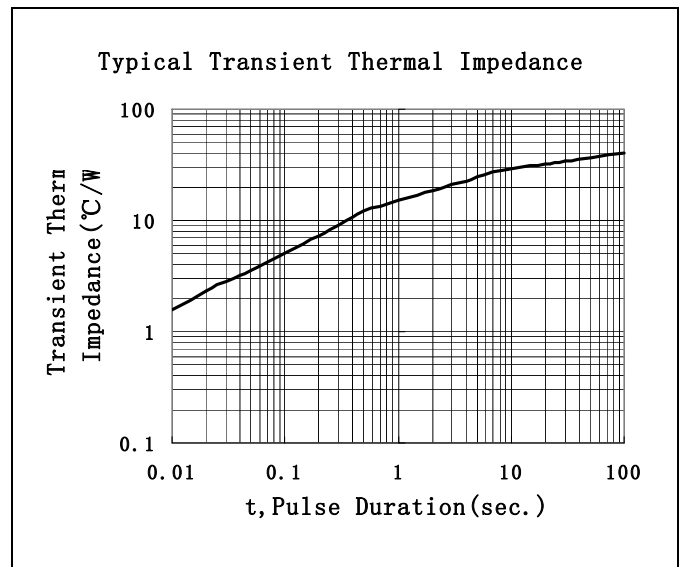
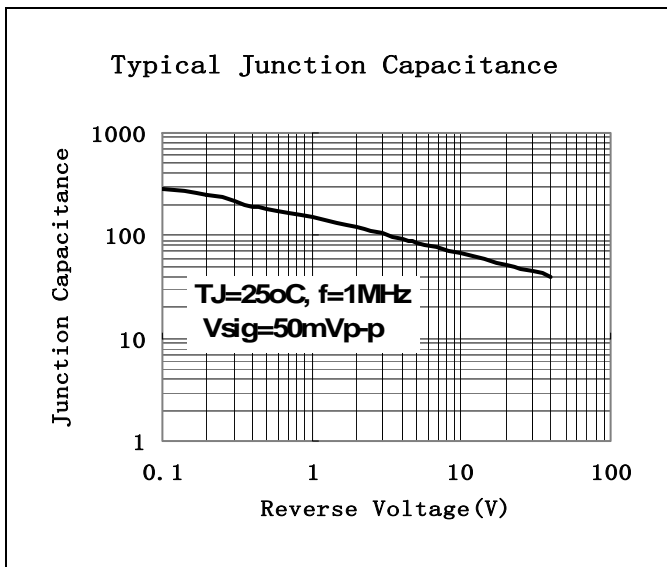
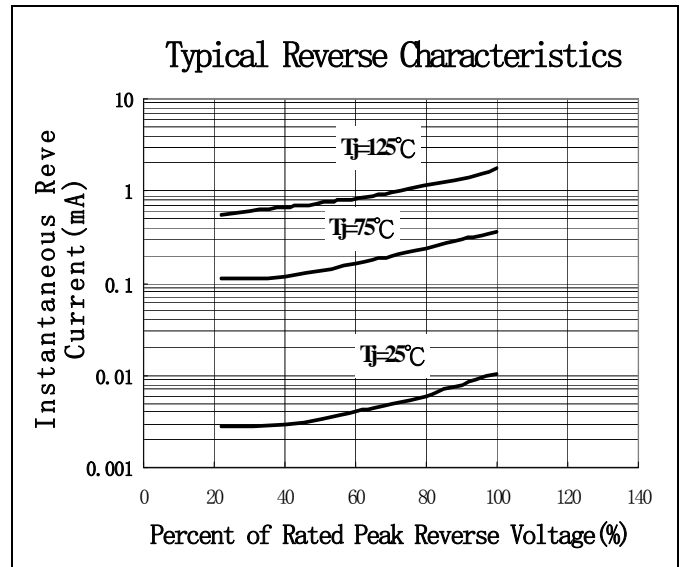
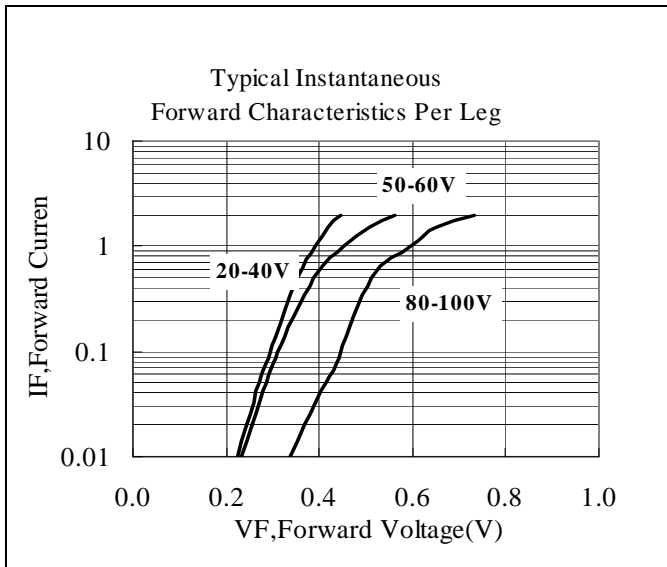
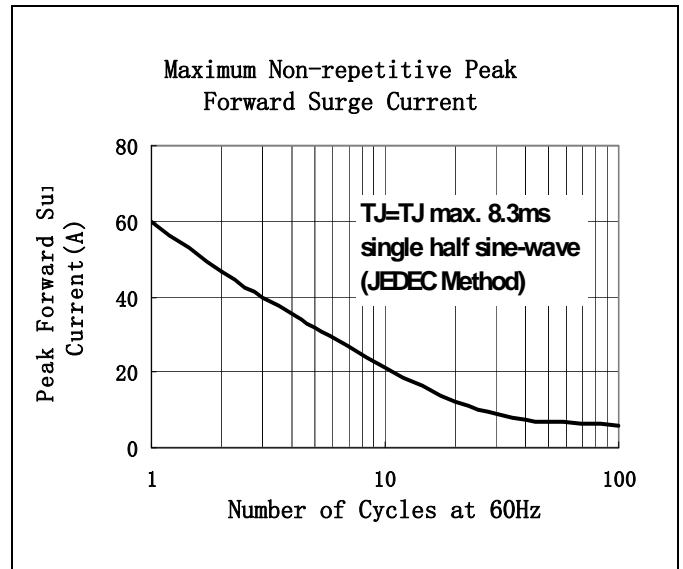
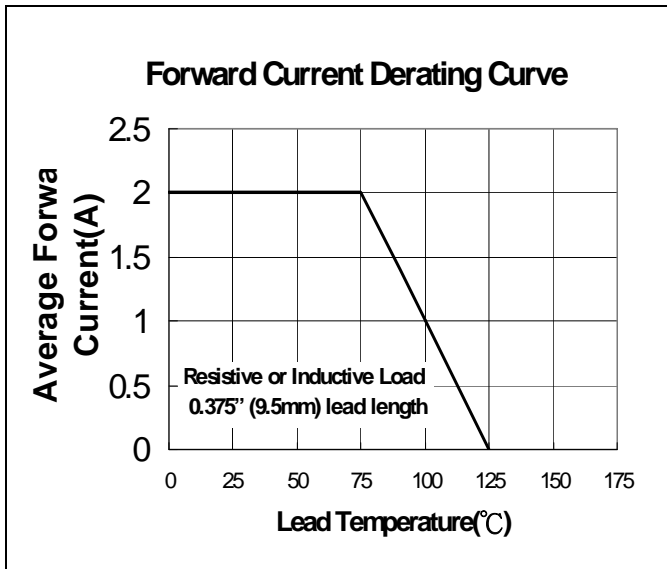
- Cases: DO-15 molded plastic
- Epoxy: UL 94V-0 rate flame retardant
- Lead: Axial leads, solderable per MIL-STD-202, Method 208 guaranteed
- Polarity: Color band denotes cathode end
- High temperature soldering guaranteed: 250°C/10seconds/.375"(9.5mm) lead lengths at 5lbs.,(2.3kg) tension
- Weight: 0.4 gram

Maximum Ratings & Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.
Single phase, half wave, 60 Hz, resistive or inductive load. For capacitive load. Derate current by 20%.

Ratings	Symbol	HSB 220	HSB 230	HSB 240	HSB 250	HSB 260	HSB 280	HSB 2100	Unit
Repetitive Peak Reverse Voltage	V_{RRM}	20	30	40	50	60	80	100	V
Surge Peak Reverse Voltage	V_{RSM}	14	21	28	35	42	57	71	V
DC Blocking Voltage	V_{DC}	20	30	40	50	60	80	100	V
Average Forward Rectified Current ($T_A=75^\circ\text{C}$)	I_{FAV}	2							A
Peak Forward Surge Current, 50Hz Half Sine-wave ($T_A=25^\circ\text{C}$)	I_{FSM}	50							A
Repetitive Peak Forward C ($f>15\text{Hz}$)	I_{FRM}	12							A
Instantaneous Forward Voltage	V_F	0.48	0.52	0.65			0.8	V	
Leakage Current ($T_J=25^\circ\text{C}$, $V_R=V_{RRM}$)	I_R	0.1							mA
Leakage Current ($T_J=100^\circ\text{C}$, $V_R=V_{RRM}$)		10							mA
Typical Junction Capacitance	C_J	170							pF
Rating for Fusing, $t<10\text{ms}$ ($T_A=25^\circ\text{C}$)	i^2t	12.5							A^2s
Thermal Resistance Junction to Ambient Air	$R_{\theta JA}$	50							$^\circ\text{C/W}$
Thermal Resistance Junction to Lead	$R_{\theta JL}$	15							$^\circ\text{C/W}$
Operating Junction Temperature Range	T_J	-65 to +125							$^\circ\text{C}$
Storage Temperature Range	T_{STG}	-65 to +150							$^\circ\text{C}$
ESD Protection Voltage	V_{ESD}	<8							KV

Characteristics Curve





DO-15 Dimension

2-Lead DO-15 Molded Plastic Package
HSMC Package Code: L

Marking:

Note:
Green label is used for pb-free packing

DIM	Min.	Max.
A	0.70	0.90
B	25.40	-
C	5.80	7.60
D	25.40	-
E	2.60	3.60

Unit: mm

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